

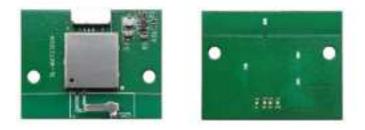
# BL-M8723DU4

802.11N 150Mbps WLAN+ Bluetooth 4.2

**USB Module Specification** 

### SHENZHEN BILIAN ELECTRONIC CO., LTD

Add: 10-11/F, Building 1A, Huaqiang idea park, Guangming district, Shenzhen, Guangdong, China Web: www.b-link.net.cn



Module Name: BL-M8723DU4	
Module Type: 802.11b/g/n 1T1R Wi	AN + Bluetooth 4.2 USB Module
Revision: V1.0	
Customer Approval:	
Company:	
Title:	
Signature:	Date:
L8-link Approval:	
Title:	
Signature:	Date:

## **Revision History**

Revision	Summary	Release Date
0.1	Initial misase	2022-01-15
0.11	Update the PCB	2022-03-31
1.0	Final release	2022-04-20

http://www.h-leik.orj.cn

э.

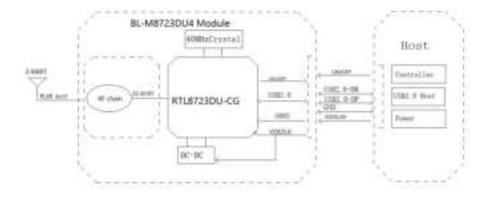
### 1. Introduction

BL-M8723DU4 is a highly integrated module built into 1 s.1 single wireless LAN and Blaetooth. Supports 1TTR WLAN baseband and RF. It supports IEEE802.11b/g/s standards and provides a maximum data rate up to 150MBps, which can provide power-rich wireless connections and reliable throughput over long distances. Support Blaetooth 2.1/3.0/4.2.

### 1.1 Features

- Operating Frequencies: 2.4-2.4835GHz
- Host Interface is USB 2.0.
- · IEEE Standards: IEEE802.11 b/g/n
- · Wireless data rate can reach up to 150Mbps
- · Bluetooth 2.1/3.0/4.2
- Module built-in antenna
- Power Supply: VDD 5.0V±0.25V

### 1.2 Block Diagram



http://www.h=letk.nej.cn

2.1

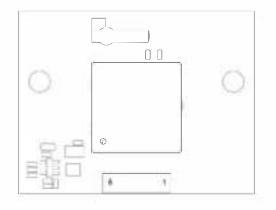
# LB-LINK®

### **1.3 General Specifications**

Module Name	BL-M8723DU4, WLAN+BT Combo Module
Chipset	RTL8723DU-CG
WiFi Standards	IEEE802.11b/g/n, 1T1R, 2.4G 150Mbps (Max)
Bluetooth Standards	V2.1/V4.2
Host Interface	USB2.0
Antenna	Module built-in antenna, max gain: 0.2dBi
Dimension	40.0*31.0*6.30mm (L*W*H), Tolerance: +/-0.15mm
Power Supply	Voltage: DC 5.0V±0.25V Standby Current: 80mA (Typ) Work Current: 350mA (Max)
Operation Temperature	-20°C to +70°C
Operation Humidity	10% to 95% RH (Non-Condensing)
Storage Temperature	-45℃ to +85℃
Storage Humidity	10% to 95% RH (Non-Condensing)
System Supported	Linux/Android/IOS/win7-win10

## 2. Pin Assignments

3



http://www.b link.net.cn

### 2.1 Pin Definition

blo	Pin-Name	Type	Description	Seppty
1	VDD5.0	de S	Power supply 5V is required (5.25V Max)	
2	USB_DM+	1/0	US8 data- (US82 0)	
3	USB_DP +	i/o	USB data- (USE2 0)	
4	GND	P	Ground connection	
5	BT_WARE	<b>3</b> .	Wake up BY (Puil high to wake up and pull low to close)	
6	ON/OFF	1	"EN" Control of SV TO 3.3V DC-DC (Internal pull High: VIH>1.2 V.VIL<0.4V.Turn on Delay#100ms)	

P: Power, I: Input, O: Output, I/O: In/Output, RF: Analog RF Port

### **3. Electrical and Thermal Specifications**

### 3.1 Recommended Operating Conditions

Paramaters		Nin	Typ	Max	Units
Ambient Operating Temperature		20	25	70	٣
Antenna gain		· · · ·	2.0	+	dBi
Supply Voltage	VDD5.0	4.75	5.0	5.25	v

### 3.2 Digital I/O DC Specifications

Symbol	Paraitieter	Min	Typ	Max	Units
VH	Input High Voltage	2.0	3.3	3.6	¥.
VIL	Input Low Voltage		0	0.9	V.

http://www.h-leik.ori.co

### 3.3 Current Consumption

Jue Case	VDD5.0 Current (average)		
Unit California	Typ	Max	Units
WFI Radio Off (Linux Driver)	76	100	mA
MiFi Disable (Linux Driver)	75		mA
MFi Unassociated (Linux Driver)	78	100	mA.
NoWLAN(Linux Driver)	74	100	mA
24G IMbps TX (1RF Test)	321	335	mA
2.4G 1Mhps RX (1RF-Test)	91	98	mA.
2.4G 11Nihps TX (1RF-Test)	285	300	mA
24G 11Mbps RX (1RF-Test)	91	98	mA
2.4G 6Mhps TX (1RF-Test)	268	278	mA.
2.4G 6Mbps RX (TRF-Test)	91	98	mA
24G MC80(HT30) TX (1RF-Text)	250	265	mA
2.4G MC80(HT20) RX (1RF Test)	91	98	mA
24G MC87(HT20) TX (1RF-Test)	187	200	mA
24G MC87(IFT20) RX (RF-Test)	91	98	mA
2.4G MCS0(HT40) TX (1RF-Test)	240	260	mA
2.4G MCSO(HT40) RX (1RF-Text)	.91	.98	mA
24G MCB7(HT40) TX (JRF Yest)	182	190	mA
2.4G MCS70ET40) RX (1RF-Test)	91	58	mA

http://www.h-leik.orj.cn

## LB-LINK

### 4. Interface Timing Specifications

### 4.1 USB Bus during power on Sequence

#### USB Bus during Power On Sequence 7.1.

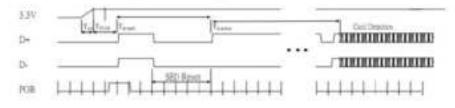


Figure 4. IETL8723DU USB live Privat Chi Sequence

Figure 4. WELF-22-DE Unit two rends to seque  $T_{part}$  to the first rends to seque  $T_{part}$ . The power of power range of details of privar management with executes power or tasks  $T_{max}$ . USB struct visit  $T_{max}$  is the datation from render attached to USB host warrag and details or privative  $T_{max}$ .

#### The preser on flow description:

After main 3.3V receptop, the internal power on reset to released by power ready detection pircuit and the power management unit will be analytical. The power management unit reading the internal negatate and clock circuits. The power management unit also sealing the USB circuits.

USB sealog circuits attach resisters to indicate the insertion of the USB device

Table 14. The typical timing range

12 - 12 / 12 / 12	Linii.	Min	Typical	Man
T.m	785	6.2	1.5	. 5
Tan	126	-	2	10
Tanat	1238	2	. 7	19
Tanton	3236	55	250	

### 4.2 Throughput Test

6

Mode	Supported mode	T/R(Mbps)	Mbps
AP Mode for 2.4G	Supported	40Mbps	-
STA Mode for 2.46	Supported	60Mbps	-
AP+STA Concurrent mode for 2.4G	Supported	AP 20Mbps	STA 30Mbps

http://www.h-letk.net.cn

## 5. WiFi & Bluetooth RF Specification

### 5.1 2,4G WiFi RF Specification

Cunditions: VDD5.0+SV: Ta	25°C				
Features	Description				
WI,AN Standard	IEEE 802.11b/g/n				
Frequency Range	2.4-2.4835GHz (2.4GHz 15	M Band)			
Modulation	802.116 DSS5: CCK, DQP5 802.11g OFDM: 64QAM,16 802.11n OFDM: 64QAM,16	QAM, QPSK, BPSK			
Date Rate	802.11b 1, 2, 5, 5, 11Mbps, 802.11g 6, 9, 12, 18, 24, 36, 48 802.11n HT20, MCS0-7, 6 802.11n HT40, MCS0-7, 1	5-722Mbps.			
Frequency Tolerance	≤ ±20ppm				
2.4G Transmitter Specificat	ions				
TX Rate	TK Power	TX Power Tolerance	EVM		
002.11b001-11Mbps	17dBm	#2.0dBm	≦-10d8		
802.11g@6Mbps	14dBm	±2.0dBm	± 10dB		
802.11g@54Mbps	14dBm	z2.0d8m	≲-25d8		
802.11n@#720_MCS0	14dBm	±2.0d8m	≦-70dB		
802.11n/EHT20_MC57	14dBm	±2.0dBm	≤ 28d8		
002.11n@91T40_MC50	14dBm	±2.0d8m	5-10d8		
802.11m@HT40_MC57	14dEm	#2.0dBm	≦ 28dB		
2.4G Receiver Specification					
ICR Rate	Min Input Level(Typ)	Max Hipet Linnil(Typ)	PER		
802.11b@1Mbps	-88dBm	-10dBm	< 8%		
802.11b@11Mbps	-79dBm	-10dBm	< 8%		
802,13g@6Mbps	-82dtim	-20d6m	< 10%		
802.11g@54Mbps	-65dBm	-20dBm	< 10%		
802.11n@98720_MC\$0	-82dBm	-20dfm	< 10%		
802.11n@98720_MC57	64dBm	20d8m	< 10%		
802.11n@HT40_MC50	-79dBm	-20dBm	< 10%		
802.11n@HT40_NICS7	-61dBin	-20dBm	× 10%		

http://www.h-leik.orj.cn

### 5.2 2.4G Authentication Channel Distribution

Regulation Domain (mib rogdomain value)	Supported Channels
FCC	1,2,3,4,5,6,7,8,9,10,11
ic	1,2,3,4,5,6,7,8,9,10,11
ETSI	1,2,3,45,6,7,8,9,10,11,12,13
MKK	1,2,3,4,5,6,7,8,9,10,11,12,13,14

### 5.3 Bluetooth RF Specification

Conditione: VDD1.0=3V; Ta:25C	2			
Features	Description			
Illuetooth Specification	Bluetooth v2.1+ED Bluetooth 4.2	Bluetooth v2.1+EDR/3.0+H5 (Bluetooth Classic _ BT BR/EDR), Bluetooth 4.2		
Frequency Range	2.4-2.4835GHz (2	(GHz ISM Band)		
Channels	Bluetooth Classic: Ch0Ch78 (For 1MHz Channels); Bluetooth Low Energy: Ch0Ch39 (For 2MHz Channels);			
Power Classes	Bluetooth Classic: Class1: Bluetooth Low Energy: Class1.5:			
Date Rate & Modulation	BR_1Mbps: GFSK; EDR_2Mbps: n/4-DQPSK; EDR_3Mbps: 8DPSK; LE_1Mbps: GFSK (Uncoded);			
Bloetooth Transmitter Specifica	tions			
Thomas	Min	Тур	Max	
TX Power				
BH_1M TX Power	0	4		
EDR, 2/3M TX Power	0	4	8	
LE_1M TX Power	0 4 8			
BR_1M Modulation Characterist	ica			
åflavg	140kHz	157kHz	175kHz	
M2max	115kHz	145kHz		

http://www.h-leik.orj.cn

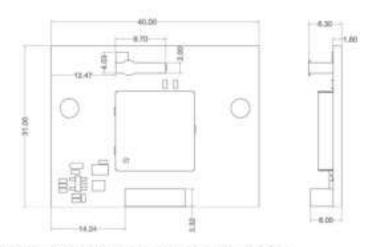
1.0

(For at least 99.9% of all &/2max)				
ΔfZavg / Δf1evg	8.0	0.98		-
EDR Madulation Accuracy				
RMS DEVM (EDR_2M)	-	8%		20%
99% DEVM (EDR_2M)	-	11%	W	
Peak DEVM (EDR_2M)	-	15%		35%
RMS DEVM (EDR. 3M)	-	8%		13%
99% DEVM (EDR_3M)		11%		20%
Peak DEVM (EDR_3M)	2	15%		25%
UL Modulation characteristics				
Affavg (LE_1M)	225kHz			2751H
Af2max (For at least 59.9% of all Af2max) (LE_1M)	185kHz	20		
Δf2avg / Δf1avg (LE_1M)	0.8	0.98		
Blaetooth Receiver Specifications				
Items	Sensitivity		Muximum Input Level	
	input Level(Typ)	BER	Input Level(Typ)	BER
BR_1M	-92dEm	20.1%	20dBm	⊴8.1%
EDR, 2M	90dilm	≤0.01%	-20dBm	±0.1%
EDR. 3M	-88dBm	≤0.01%	-20d8m	±0.1%
LE 1M	90dBm	≤30.8%	-20dBm	sti.1%

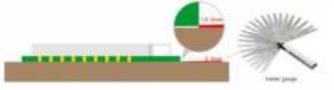
http://www.h-leik.orj.cn

### 6. Mechanical Specifications

6.1 Module Outline Drawing



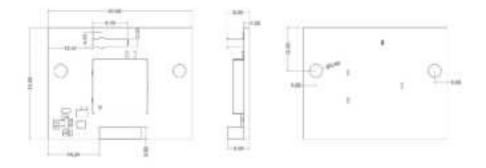
Module dimension: 40.0\*31.0\*6.30mm (L\*W\*H; Tolerance: ±0.15mm)



Module Bow and Twist ≤0.1mm

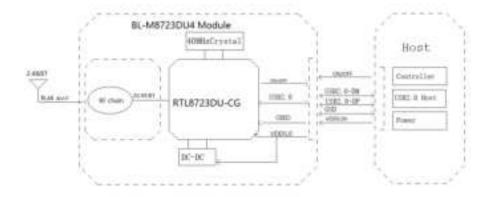
http://www.th-link.net.cn

### 6.2 Mechanical Dimensions



## 7. Application Information

7.1 Typical Application Circuit

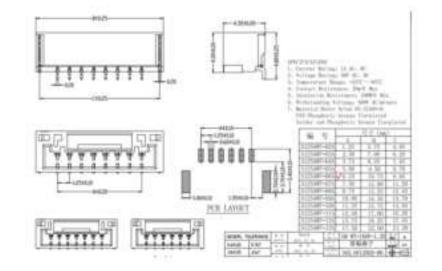


http://www.th-link.net.cn

11.



### 7.2 Connector Specification



## 8. Key Components Of Module

No.	Parts	Specification	Manufacturer	Nobi
1	Chipset	RTL8723DU-CG.	Realtek	
2 РСВ		BL M8723DU4	Shen Zhen Tie Fa Technology limited	
			MILLION SOURCE PRINTED CIRCUIT BOARD CO., LTD	
			Quzhou Suelord Electronics Co., Ud	
3 Crystal		Lucki Electronics Co., Ltd		
	Crystal	40MHz-3225	Shendhen Kalyuesiang Electronics Co., Ltd	
			Chengde Oscillator Electronic Technology Co., Ltd.	
4	PMIC	sotza s	TMI	_
	rmn.		SILERGY	

http://www.ti-link.net.cn

## LB-LINK

### 9. Package and Storage Information

### 9.1 Package Dimensions



Package specification:

- 1. 24 modules per blister plate and 288 modules per box.
- 2. The blister is bound with wire membrane and put into anti-static vacuum bag.
- 3. Put 1 bag of dry beads (20g) in each anti-static vacuum bag. 1 pcs 3 point humidity card.
- 4. The outer box size is 35.2\*21.5\*15.5cm.

#### 9.2 Storage Conditions

#### Absolute Maximum Ratings:

- Storage temperature: -45°C to +85°C
- Storage humidity: 10% to 95% RH (Non-Condensing)

### **Recommended Storage Conditions:**

- Storage temperature: 5°C to +40°C
- Storage humidity: 20% to 90% RH

Please use this Module within 12month after vacuum-packaged. The Module shall be stored without opening the packing. After the packing opened, the Module shall be used within 72hours. When the color of the humidity indicator is the packing changed, The Module shall be baked before use. Baking condition: 60°C, 24bours, 11ime.

#### ESD Sensitivity:

11

- ESD Protection: 4KV(HBM ,Maximum rating)
- The Module is a static sensitive electronic device.
- Do not operate or store near strong electrostatic fields.
- Take proper ESD precautions!



ESD CAUTION

http://www.ti-liek.riet.cn

### **FCC Statement**

This device has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This device generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications.

However, there is no guarantee that interference will not occur in a particular installation. If this device does cause harmful interference to radio or television reception, which can be determined by turning the device off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

--Reorient or relocate the receiving antenna.

--Increase the separation between the device and receiver.

--Connect the device into an outlet on a circuit different from that to which the receiver is connected.

--Consult the dealer or an experienced radio/TV technician for help

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment

The antennas used for this transmitter must be installed to provide a separation distance of at lea st 20 cm from all

persons and must not be co-located for operating in conjunction with any other antenna or transmitter.

This device complies with Part 15 of the FCC Rules and contains licence-exempt transmitter(s)/receiver(s) that comply with Innovation, Science and Economic Development Canada's licence-exempt RSS(s). Operation is subject to the

following two conditions: (1) this device may not cause harmful interference, and

(2) this device must accept any interference received, including interference that may cause undesired operation

Please notice that if the FCC identification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording such as the following: "Contains FCC ID: 2AL6K-BL-M8723DU4" any similar wording that expresses the same meaning may be used.

The ISED certification label of a module shall be always clearly visible when installed in the host product; otherwise, the host product must be labelled to display the ISED certification number for the module, preceded by the word "contains" or similar wording expressing the same meaning, as follows: Contains IC: 20944-BLM8723DU4

The module is limited to OEM installation ONLY. The OEM integrator is responsible for ensuring that the end-user has no manual instruction to remove or install module.

Cet appareil contient des émetteurs / récepteurs exemptés de licence conformes aux RSS (RSS) d'Innovation, Sciences et Développement économique Canada. Le fonctionnement est soumis aux deux conditions suivantes : (1) Cet appareil ne doit pas causer d'interférences. (2) Cet appareil doit accepter toutes les interférences, y compris celles susceptibles de provoquer un fonctionnement indésirable de l'appareil